



BIGTREETECH

# Shenzhen Biqu Technology 3D Printer G0B1 Project



BIGTREETECH


BIGTREETECH\_Manta\_M4P\_V2.1\_220608

MCU: STM32G0B1RCT6  
MODULE: RPI-CM4Lite-R1-3 or H616  
DCDC: TPS5450DDAR  
LDO: AMS1117-3V3  
DIRVE: TMC5160  
USB\_HUB: FE1-1S-QFN28BCN

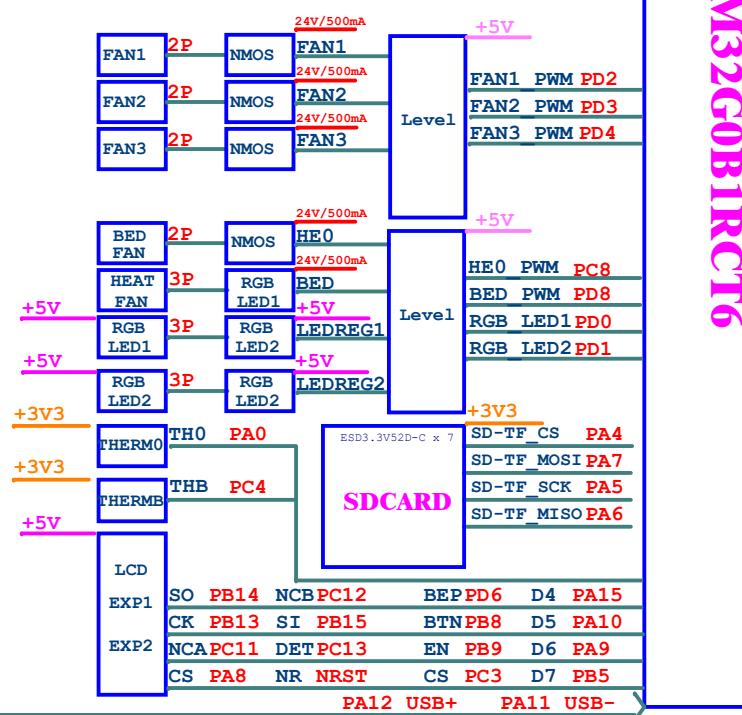
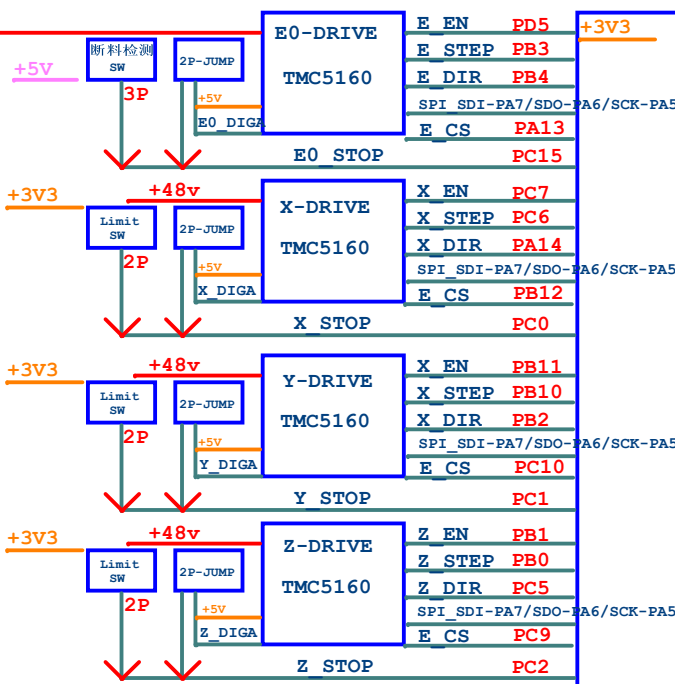
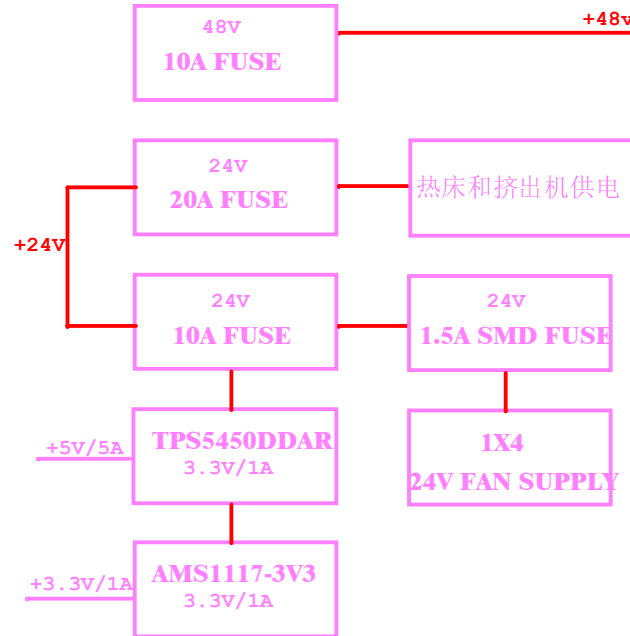
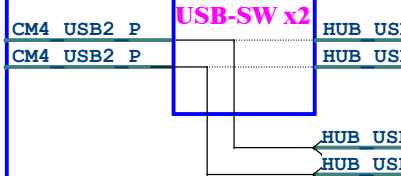
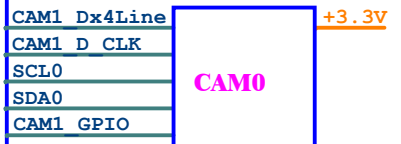
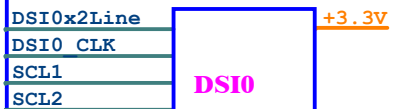
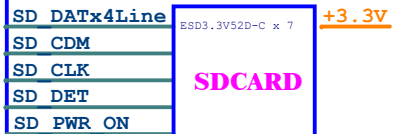
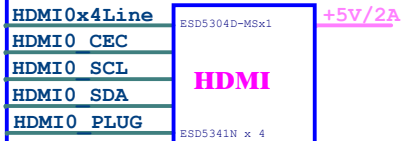
 BIGTREETECH		<b>Shenzhen Biqu Technology Co., Ltd.</b>	
Title		BIGTREETECH_Manta_M4P_V2.1	Design Bron Bai
Size A	Document Number 01_Cover Page		Rev V2.1
Date: Thursday, July 07, 2022		Sheet 1	of 24

## BIGTREETECH\_Manta\_M4P\_V2.1 INDEX

01_Cover Page
02_Index
03_Function Block Diagram
04_Revision History
05_DCDC 5V-10A
06_MCU_STM32G0B1
07_DRIVER SPI LEVEL
08_STM32_MOTOR DRIVER-E
09_STM32_MOTOR DRIVER-X
10_STM32_MOTOR DRIVER-Y
11_STM32_MOTOR DRIVER-Z
12_STM32_FAN&RGBLED_CNTR
13_STM32_SD Card
14_STM32_Thermistor
15_STM32_SPI-DSP
16_CB1&CM_BTBA
17_CB1&CM_BTBB
18_CB1&CM_HDMI
19_CM4_DSI1_CAM1
20_CB1&CM_2.0HUB
21_CB1&CM_ETHERNET
22_CB1&CM_TF_CARD
23_CB1&CM_RESE_IO&CM4-FAN
24_CB1&CM_USB-OTG

		<b>Shenzhen Biqu Technology Co., Ltd.</b>	
Title		BIGTREETECH_Manta_M4P_V2.1	
Size A4		Document Number 02_Index	
Date: Thursday, July 07, 2022		Sheet 2 of 24	
		Design Bron Bai Rev V02	

H616&CM



STM32G0B1RCT6

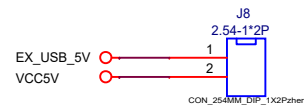
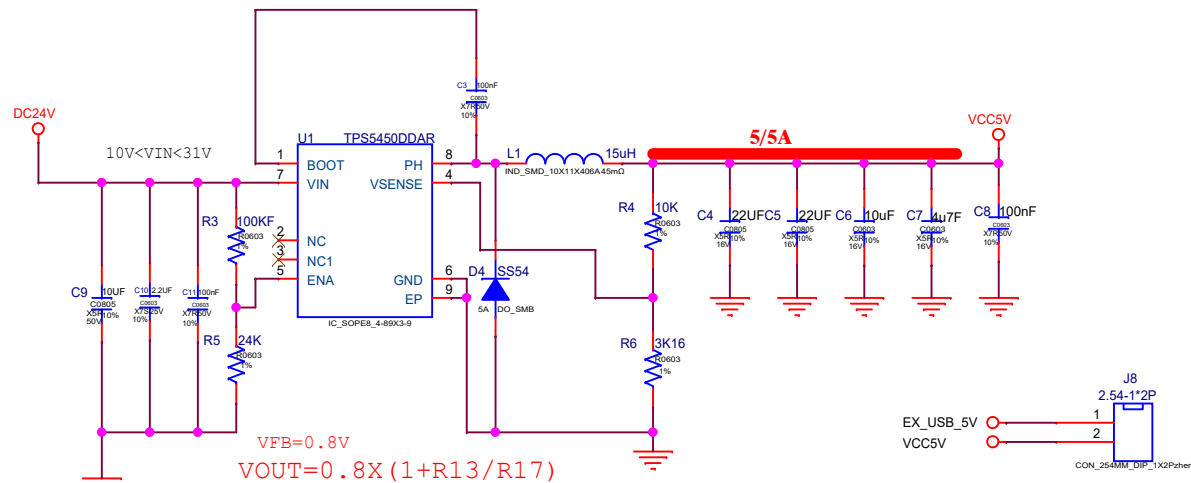
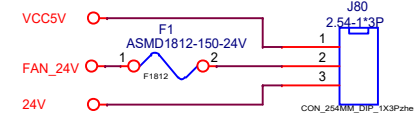
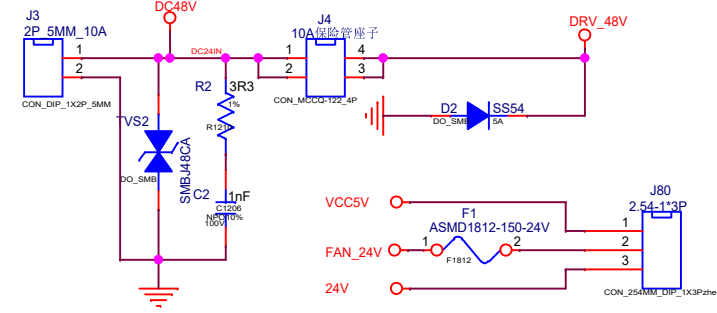
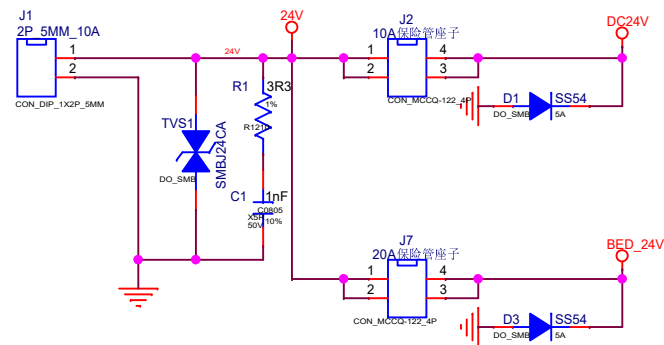
Revision History

Version	Date	Author	Change Note	Approved
V01	2022.01.06	Byron Bai	1. BTT E3 SKR MINI V3.0的基础上修改 。 2. 树莓派模组RPI-CM4Lite-R1-3作为核心算法板。 3. 所有的IO口保护由压敏电阻改为ESD。 3. 所有的器件增加描述、厂商PN、厂商名称等。 <div>注：V02只是修改PCB外形</div>	
M4P_V1.0	2022.03.30	Byron Bai	<div>MCU</div> <div>1. X轴的 CS 和 DIR 所用的 MCU 的 IO 交换一下。（即X轴的DIR和下载口SWCLK复用，之前CS和下载口SWCLK不在一起复用，单IO口使用）。</div> <div>2. SPI1 的 MISO, MOSI, SCK 没有连接到MCU上（与板载的 MicroSD 卡公用，即TMC5160的SPI1 MISO, SPI1 MOSI, SPI1 SCK, 分别用SD-TF MOSI 【PA7】 SD-TF MISO 【PA6】 SD-TF CS 【PA5】连接；J58 的SPI1 MISO, SPI1 MOSI, SPI1 SCK也是如此连接）。</div> <div>3. 增加驱动高低压选择跳线帽没有 24V和48V转换。加2.54mm3P插针。</div> <div>4. 更改RGB 线序。正常的是 5V 信号线。（已经更改）。</div> <div>5. 驱动的 CS (UART) 脚没有隔离。用MOS+3个10电阻。</div> <div>6. 改变热床、挤出机的开关NMOS封装为DFN和TO252。</div> <div>7. 风扇的保险改为3A/F1812。</div> <div>SoC</div> <div>1. CSI、DSI 改为15pin 1.0mm间距，全部都用2Line 【 朝上接】</div> <div>2. USB hub 换封装为QFN24。</div> <div>3. CM4和H616统一改为 USB hub 挂载 USB 设备。</div> <div>4. HDMI旁边要放USB，使用HDMI屏幕时插USB触摸用的。</div> <div>5. 40pin GPIO尽量保留并且与树莓派线序一致。尽量。</div> <div>6. 取消PCIE和PCIE 12V DCDC。图纸P6&amp;P17，待决定。</div> <div>7. 取消J73，只保留nRFIBOOT EEPROM nWP增加拨码开关，GLOBAL_EN加个上拉电阻 (NC) RUN_PG加个下拉电阻 (NC)。</div> <div>8.取消RTC。图纸P25。</div> <div>9.取消HUB的灯。图纸P20。</div> <div>10.HOST USB去掉一个电解电容。</div> <div>11.取消HUB电源开关。</div> <div>注：第三版由"BQ_CM4-H616_Carrier_Board_v2"更改为"BIGTREETECH_Manta_M4P_V1"</div>	
M4P_V2.0	2022.05.06	Byron Bai	1. TF CARD电源由CM4SD 3v3变更为"CM4_3V3"; 2. 变更J75的支持A型USB直插座子封装。 3. 变更了USB开关，电压启动方式。 4. 变更了J63右边的孔径，跟板厂沟通要走正公差。 5. J48/J51/J1/J3的1.1mm孔径不变，跟板厂沟通要走正公差。 7. J46由3PIN插针更改为3P 2.54mm插座。 8. J59 78PIN, 连接CM4_3V3.供CM4内部3.3v参考电压,同时核心板H616_PC16NC。 9. 电机使能R150,R154,R153,R159由下拉变更为上拉 3.3V。 10. Q7,Q15,Q10,Q11,Q12,Q13,源极上拉由10K 变更为 0R. 源极下拉和漏极上拉由10K变更为 1.8 K。 11. HUB U16的晶振电容贴错，拆掉保留位置，预留12PF负载电容位置。 12. DSI插座和CSI插座，增加丝印标识。 13. Q14 R161接"HEATING"这端变更为接地下拉。	

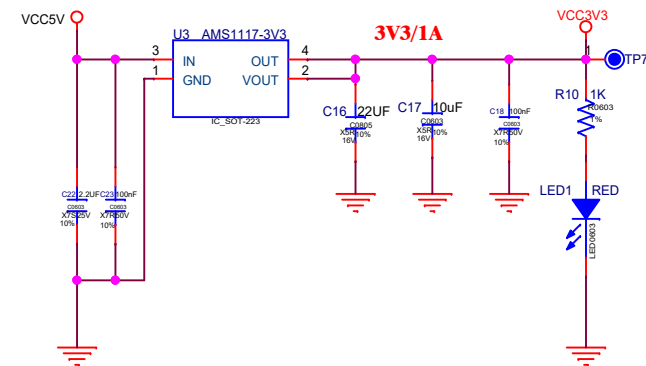


Shenzhen Biqu Technology Co., Ltd.

Title		Design
BIGTREETECH_Manta_M4P_V2.1		Byron Bai
Size	Document Number	Rev
B	04_Revision History	V2.1
Date: Thursday, July 07, 2022		Sheet 4 of 24



External USB5V comes in, only for system debugging.

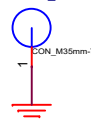


DC-DC\_3V3/1A

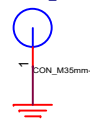
H1  
HOLE\_3R20



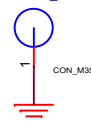
H2  
HOLE\_3R20



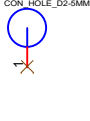
H3  
HOLE\_3R20



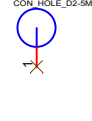
H4  
HOLE\_3R20



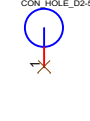
H5  
CON\_HOLE\_D2-5MM  
CON\_HOLE\_D2-5MM



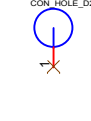
H6  
CON\_HOLE\_D2-5MM  
CON\_HOLE\_D2-5MM



H7  
CON\_HOLE\_D2-5MM  
CON\_HOLE\_D2-5MM

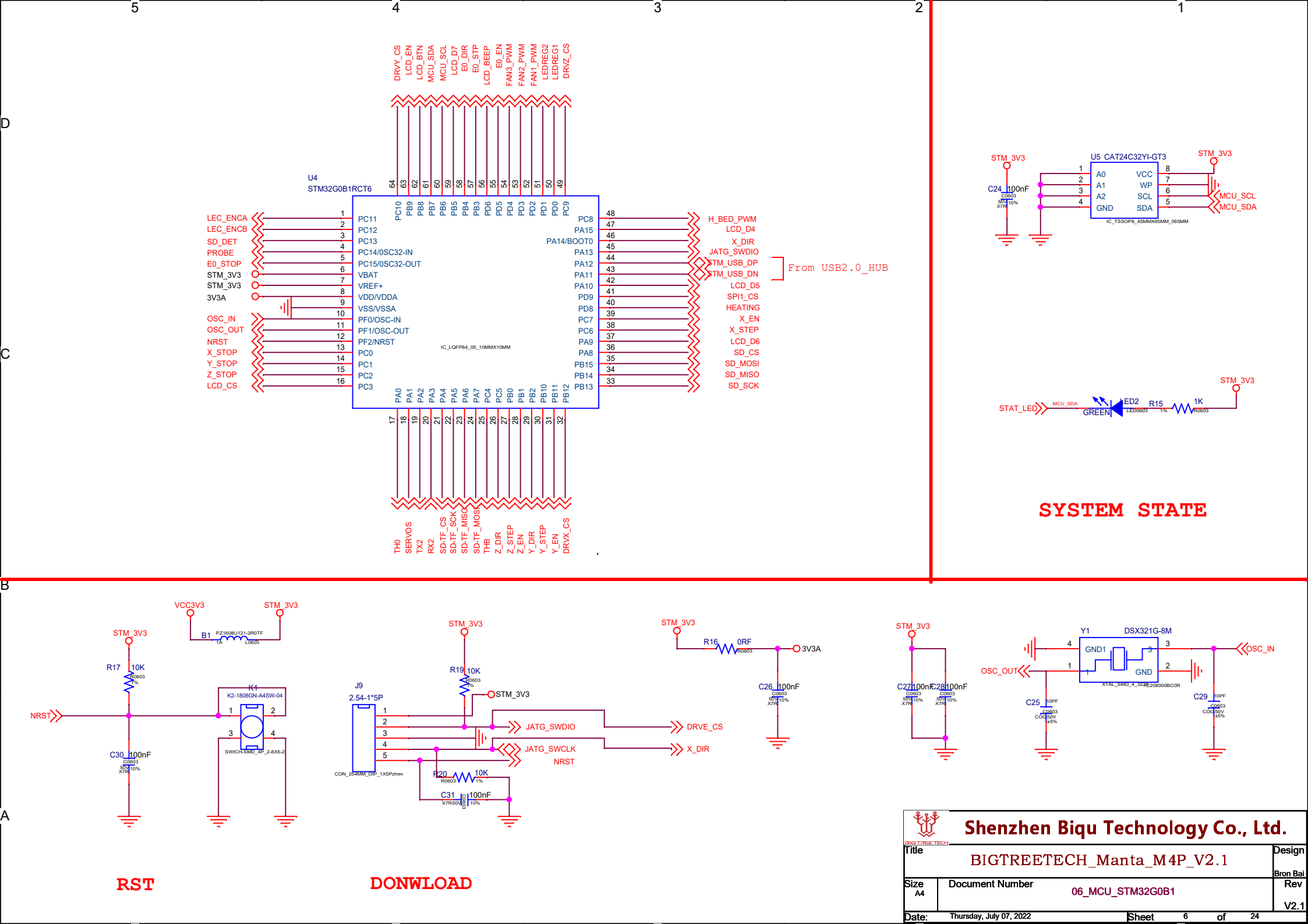


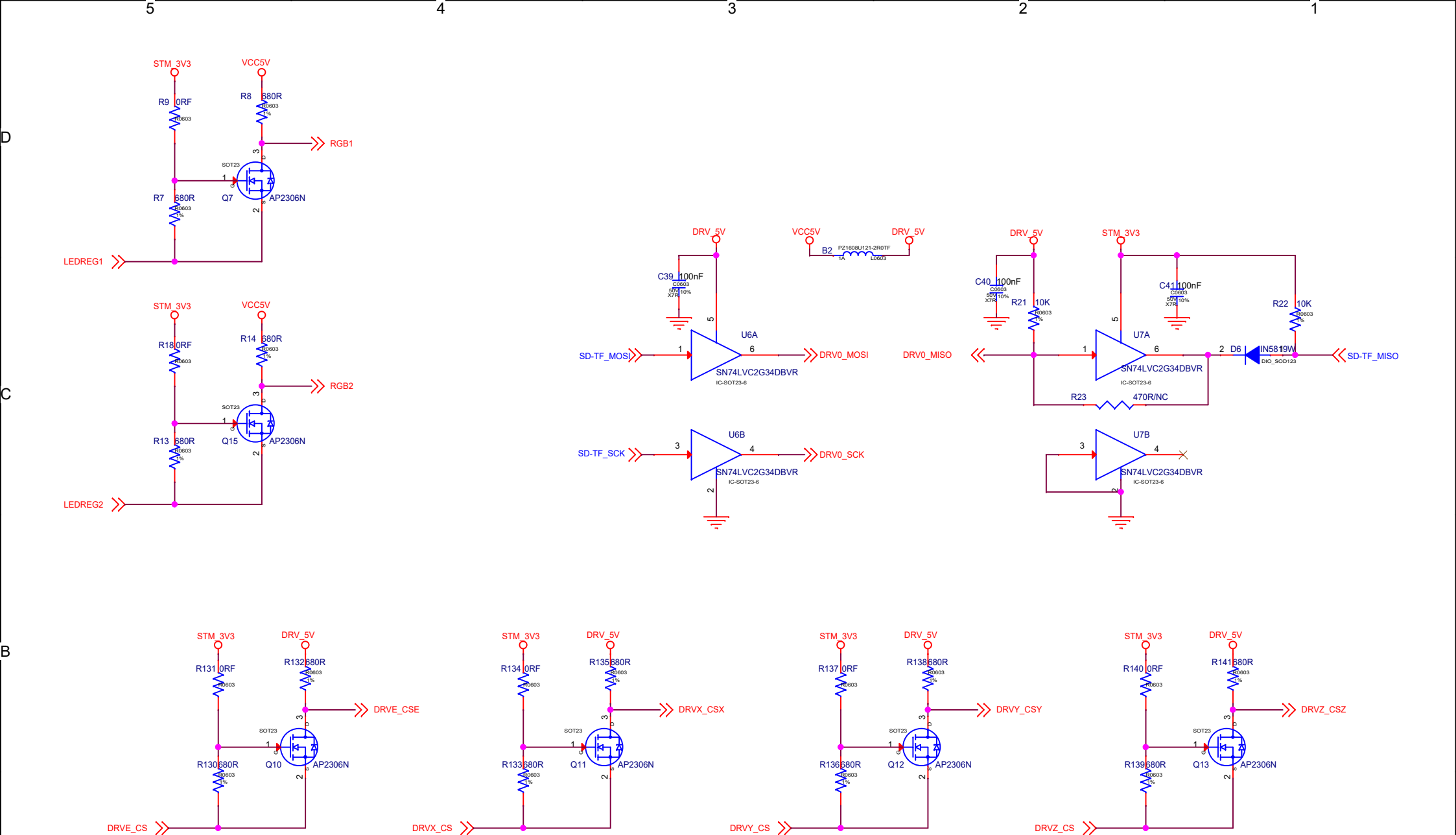
H8  
CON\_HOLE\_D2-5MM  
CON\_HOLE\_D2-5MM




Shenzhen Biqu Technology Co., Ltd.

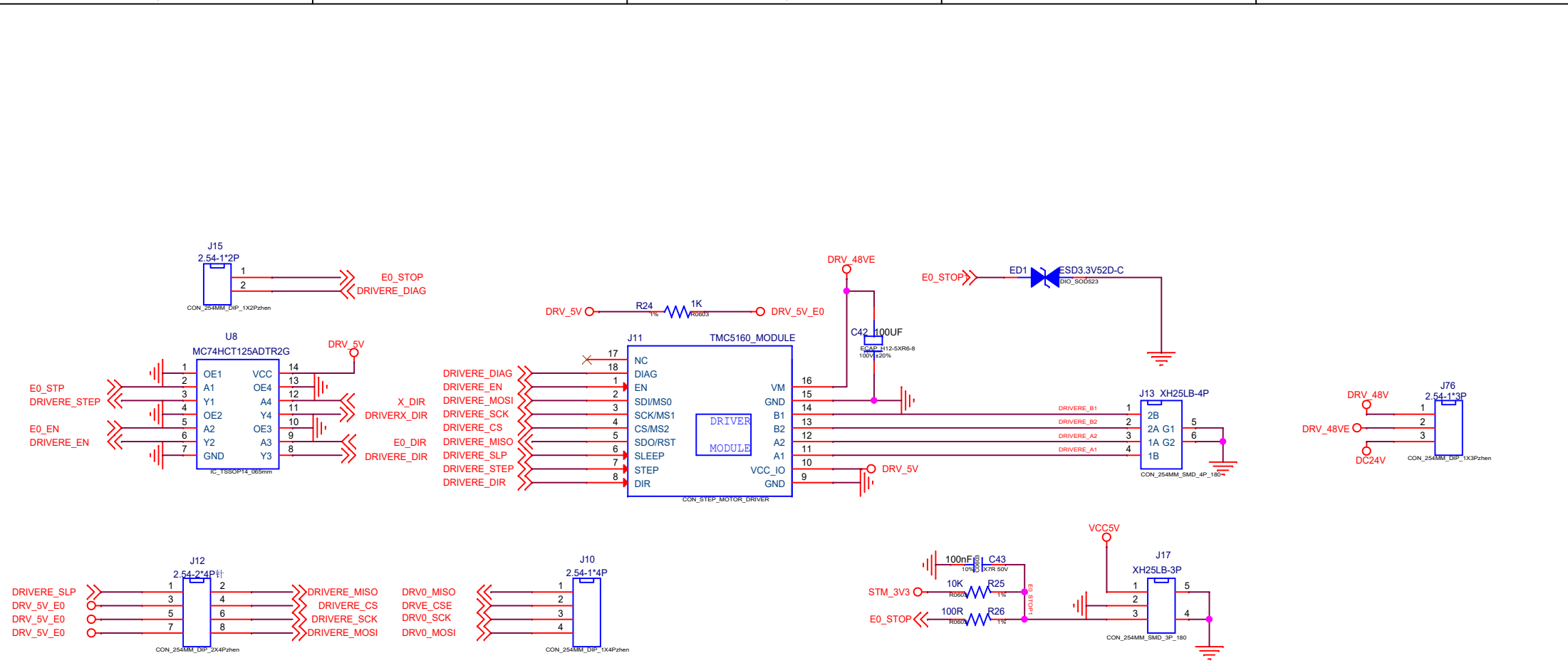
Title		BIGTREE TECH	
Size		Document Number	
A4		05_DCDC_5V-10A	
Date:		Thursday, July 07, 2022	
Sheet		5 of 24	
Rev		V2.1	





## TMC5160 SPI IO level

 <b>Shenzhen Biqu Technology Co., Ltd.</b>			
Title		BIGTREE TECH_Manta_M4P_V2.1	
Size A4		Document Number 07_DRIVER_SPI_LEVEL	
Date: Thursday, July 07, 2022		Sheet 7 of 24	
Rev		V2.1	



**JUMP**

**Material stop detection**

**E0-DRIVE**

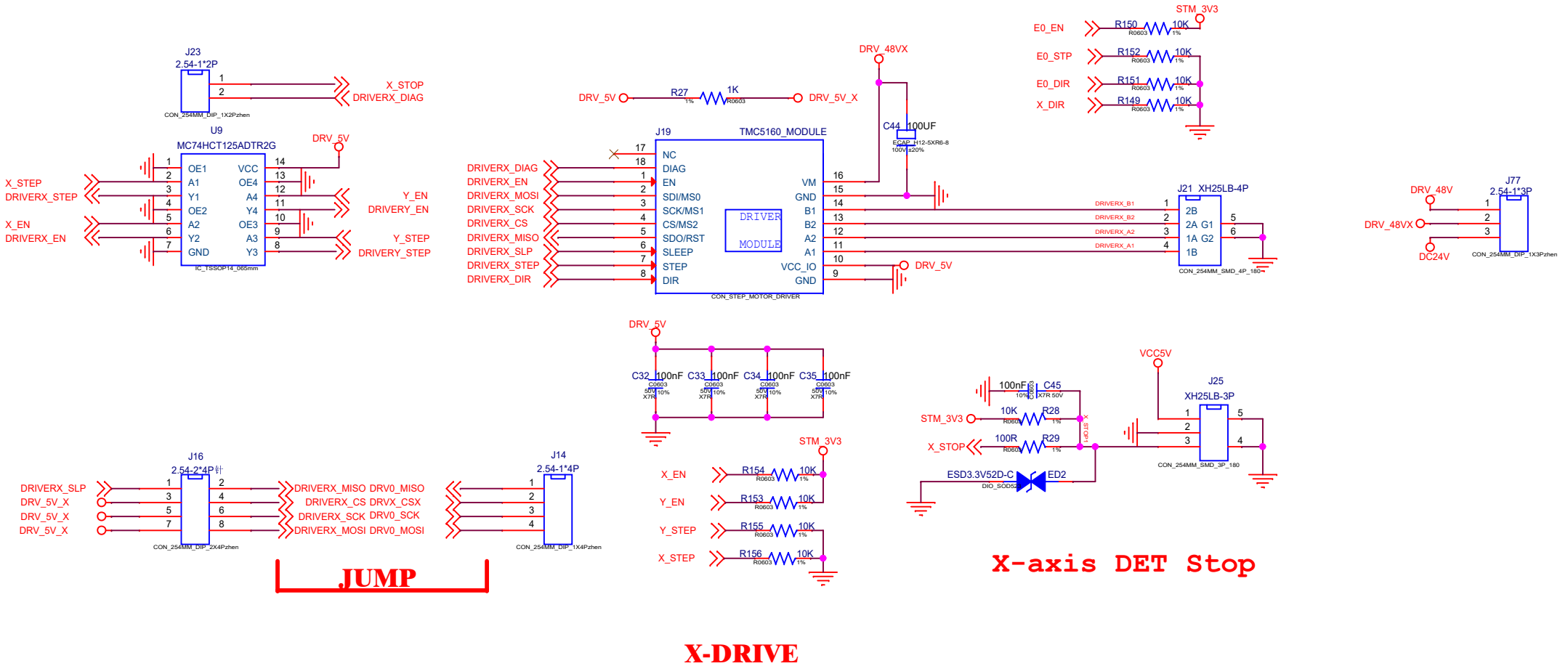


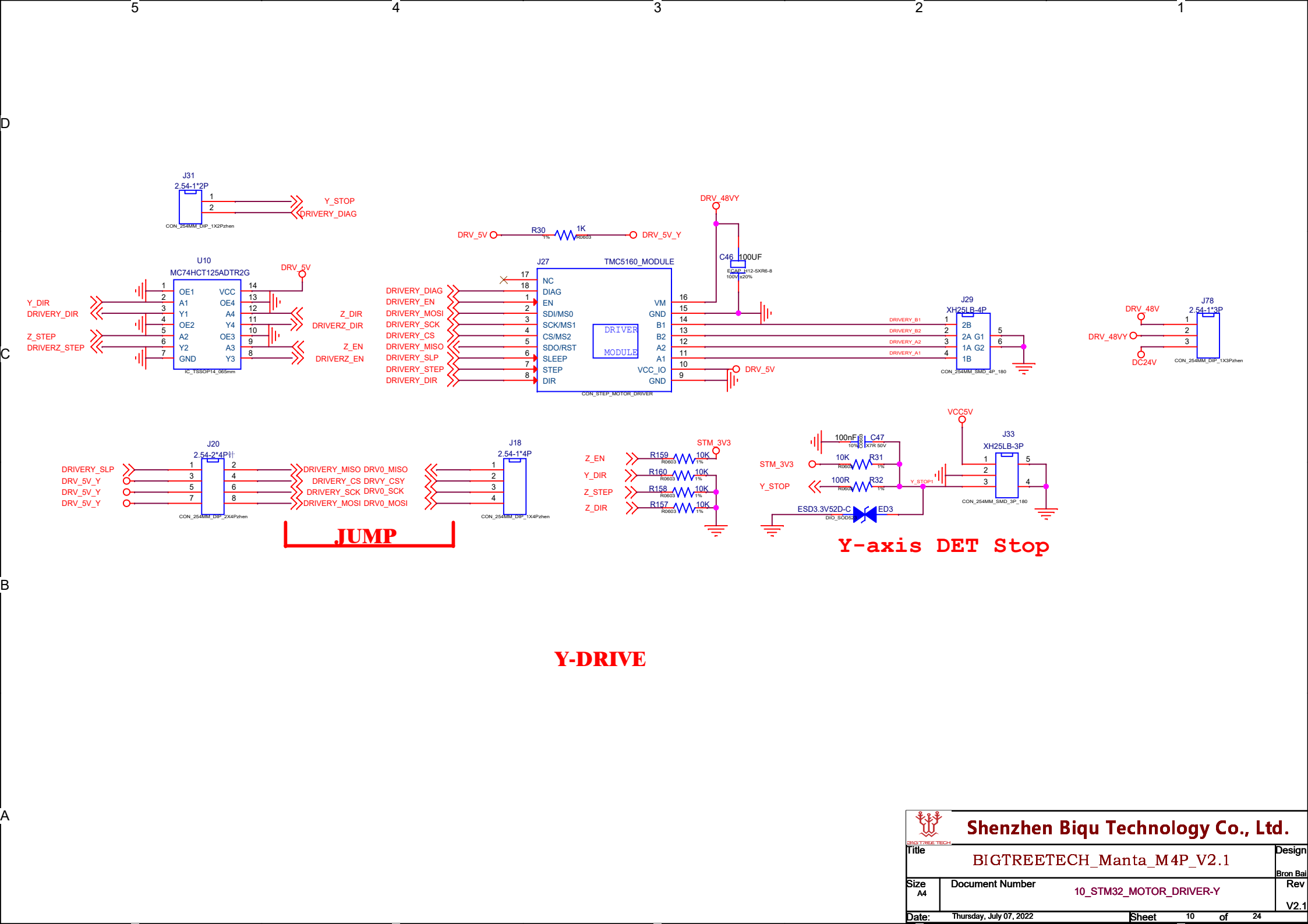
D

C

B

A



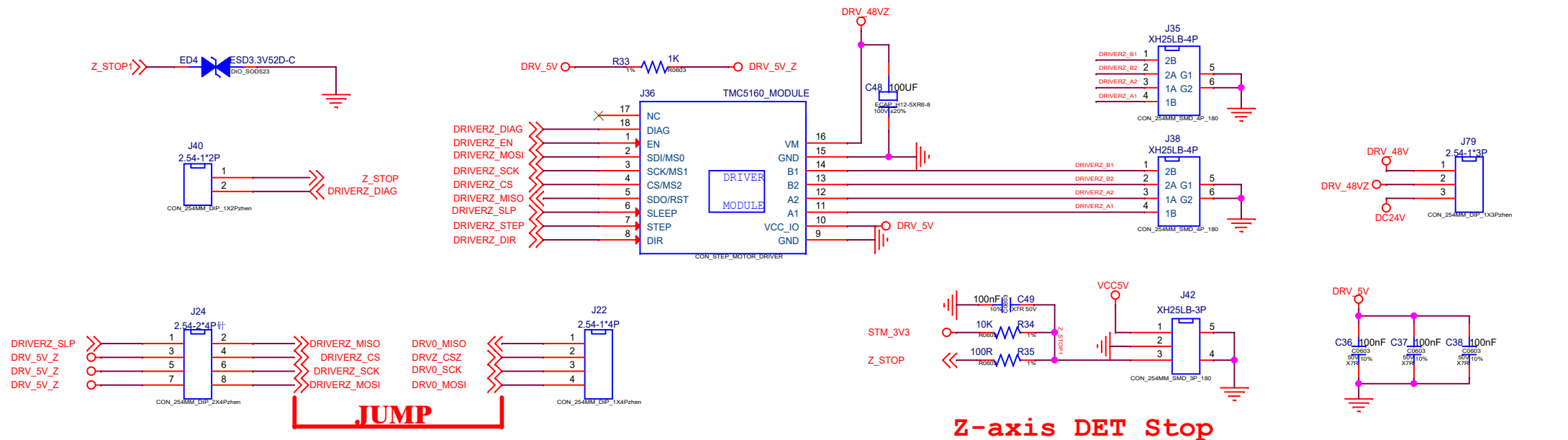


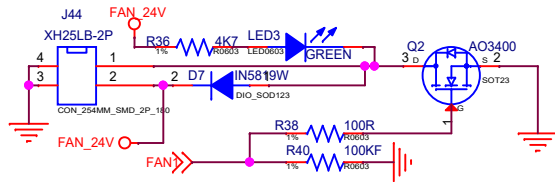
D

C

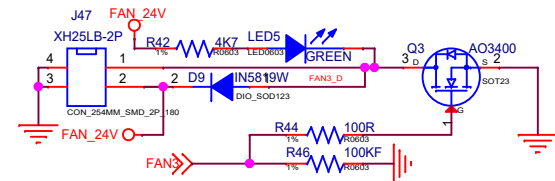
B

A

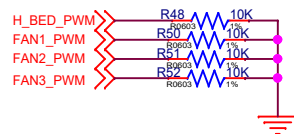
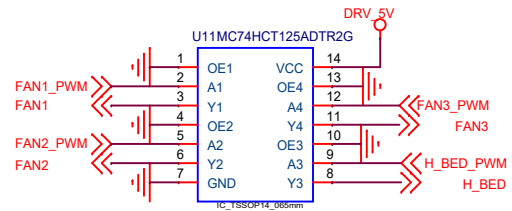
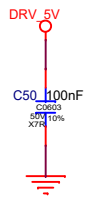
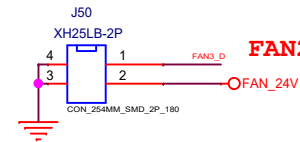




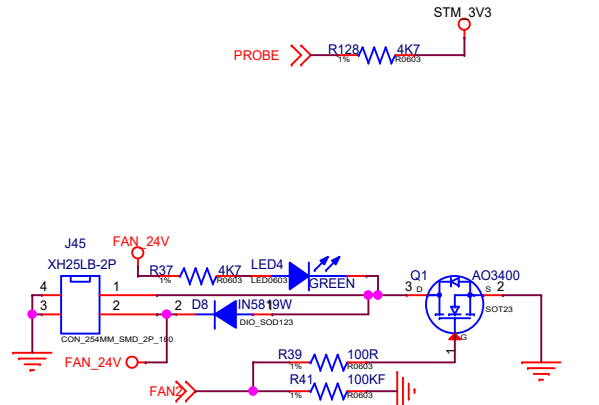
FAN0



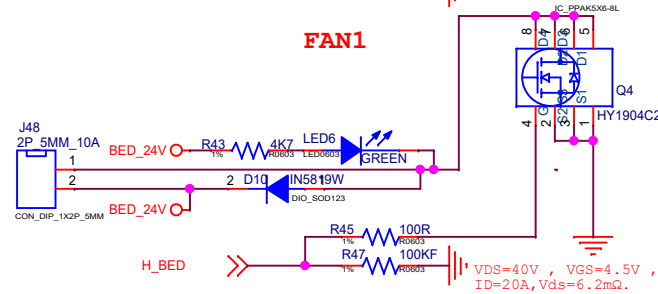
FAN2



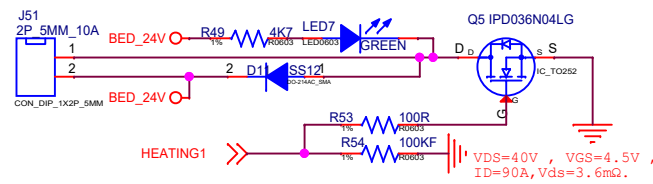
FAN&RGBLED\_CTR



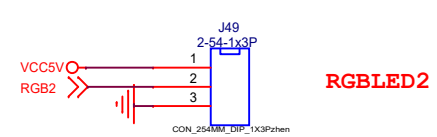
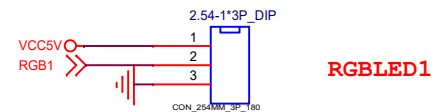
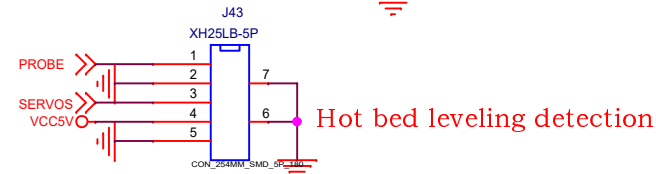
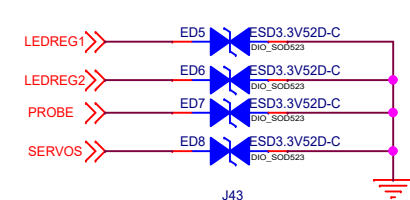
FAN1



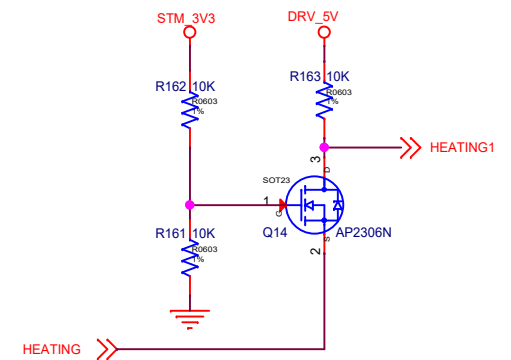
HEATING



HEAT\_BED



RGB\_LED

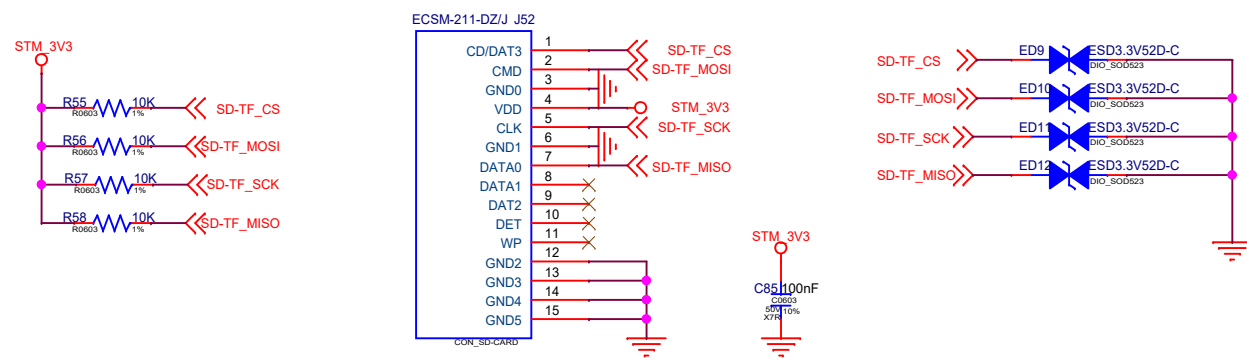


D

C

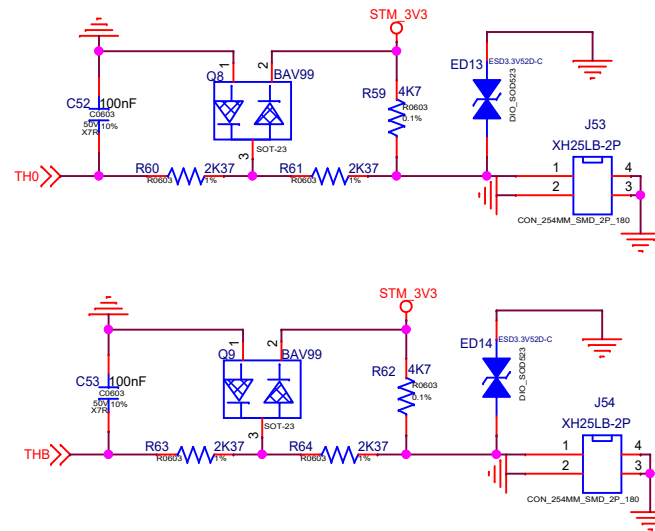
B

A



Description: Onboard SD card, drive SPI, expand SPI share G0B1 SPI1 (PA4, PA5, PA6, PA7)

## SD\_Card

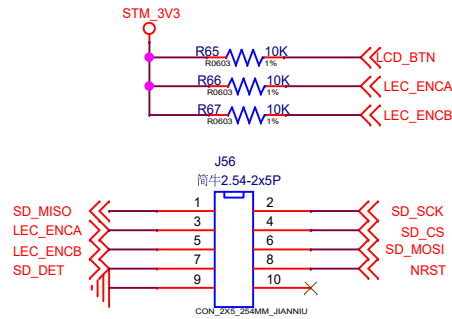


## Thermistor



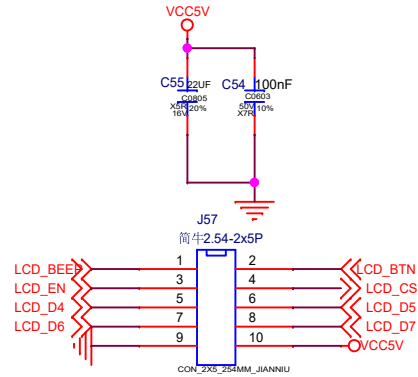
Shenzhen Biqu Technology Co., Ltd.

Title		BIGTREE TECH_Manta_M4P_V2.1	Design
Size		Document Number	Rev
A4		14_STM32_Thermistor	V2.1
Date:		Thursday, July 07, 2022	Sheet 14 of 24



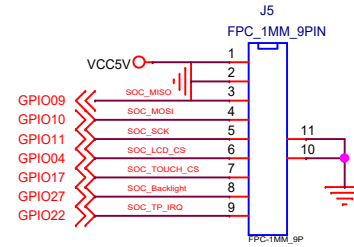
MCU\_DISP\_EXP2

SPI in EXP-2 uses G0B1 SPI2 (PB13, PB14, PB15, PA8)

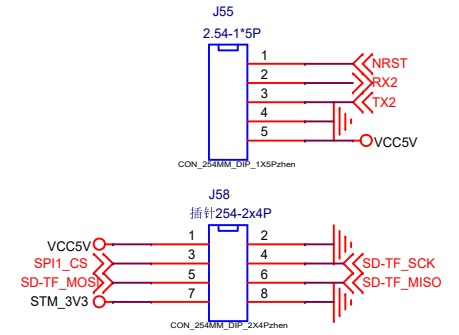


MCU\_DISP\_EXP1

Description: Onboard SD card, drive SPI, expand SPI share G0B1 SPI1 (PA5, PA6, PA7)



Soc\_DIS



MCU\_DISP\_SPI1\_EXP3

Description: onboard SD card, driver SPI, Expand SPI to share G0B1 SPI1 (PA5\PA6\PA7/PD9)

# Display



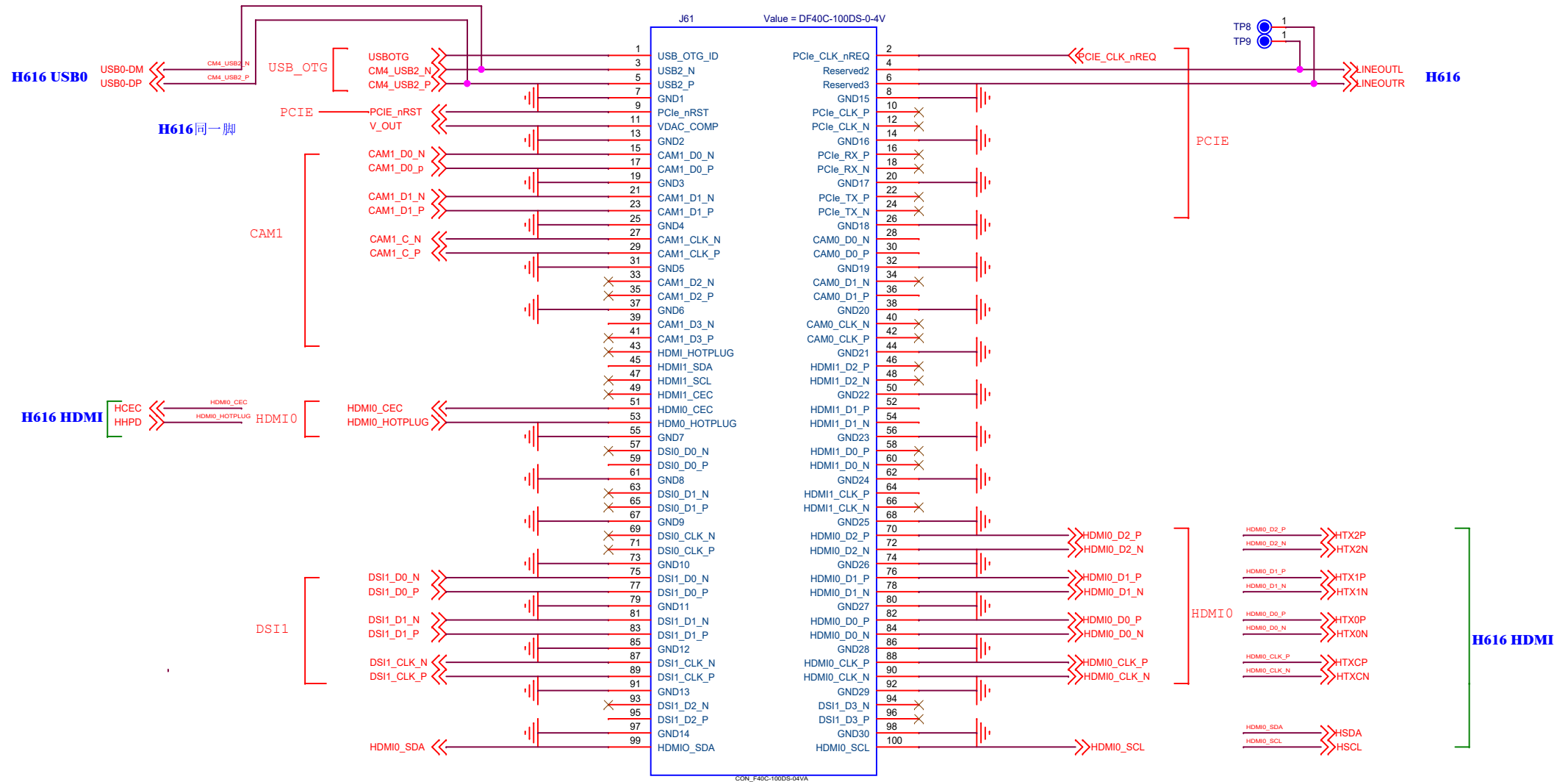


D

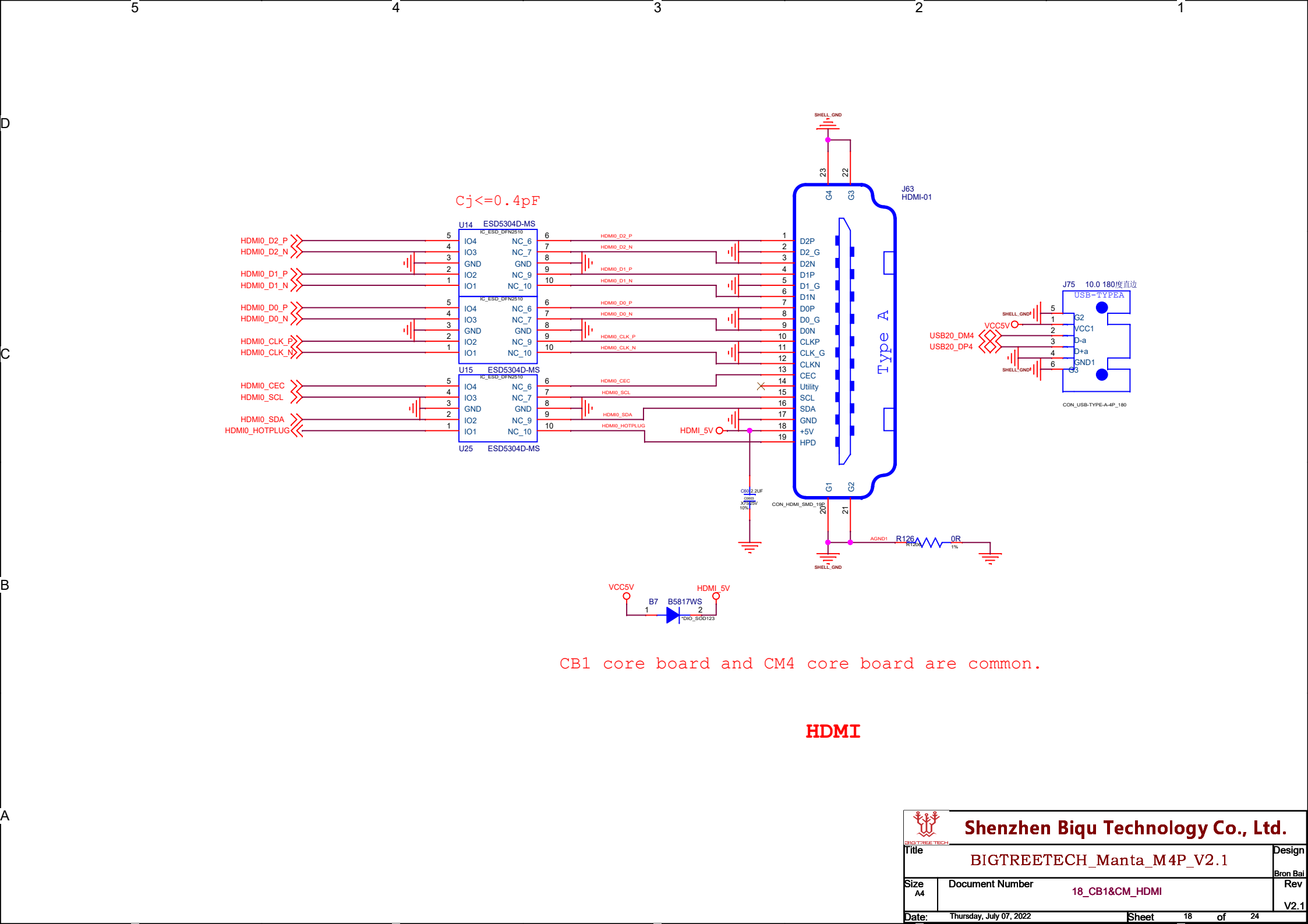
C

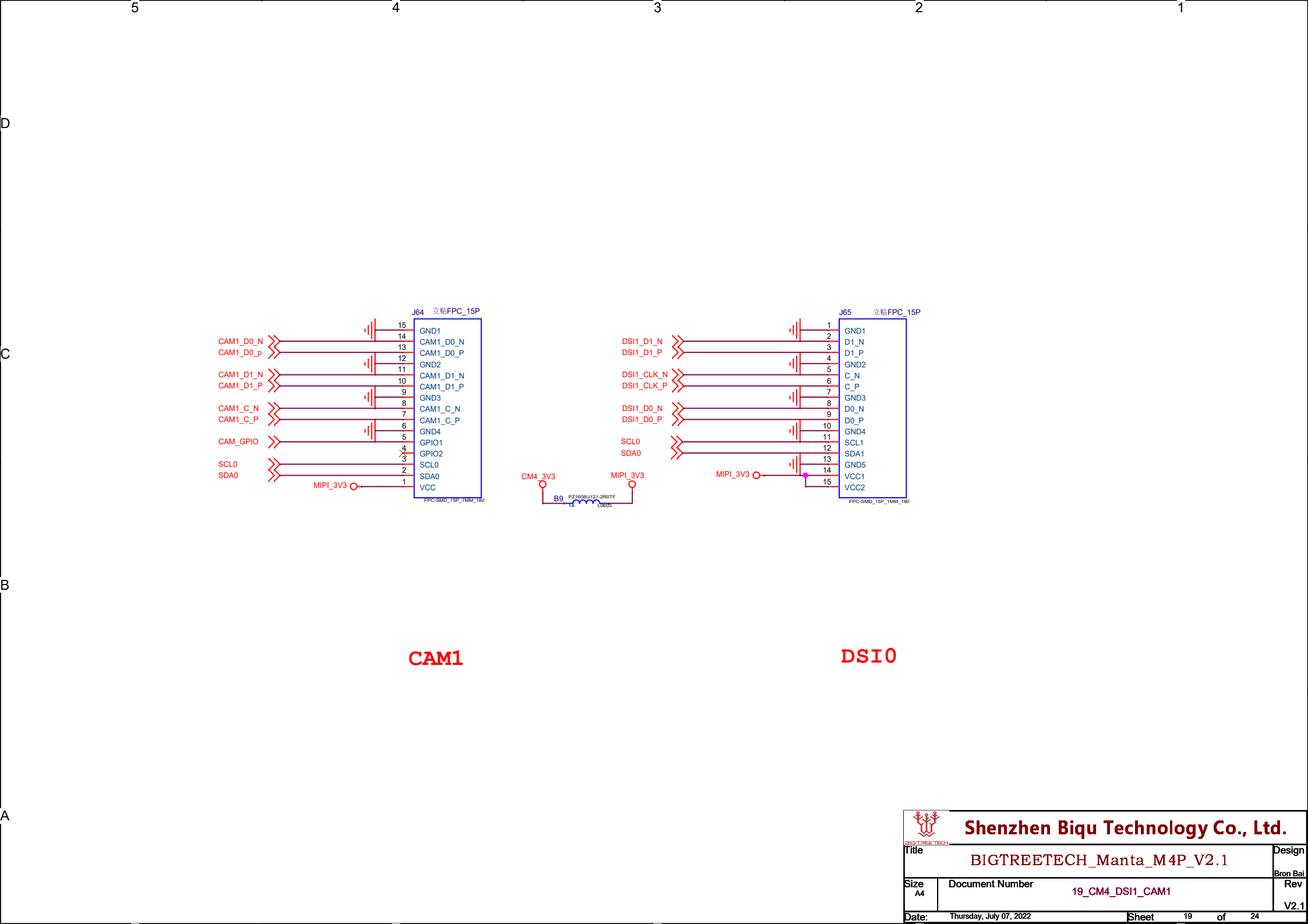
B

A

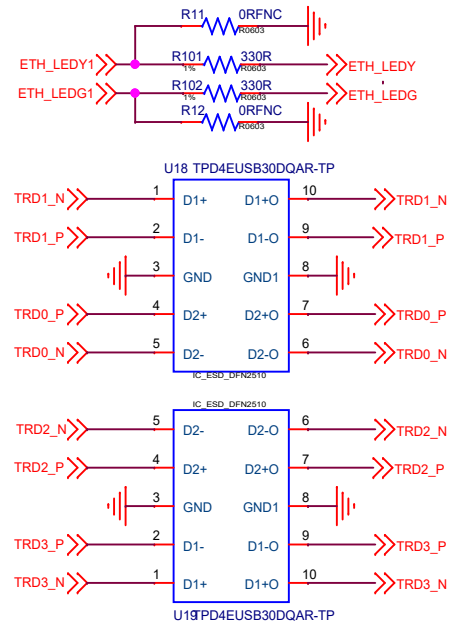


CB1 core board and CM4 core board are common.

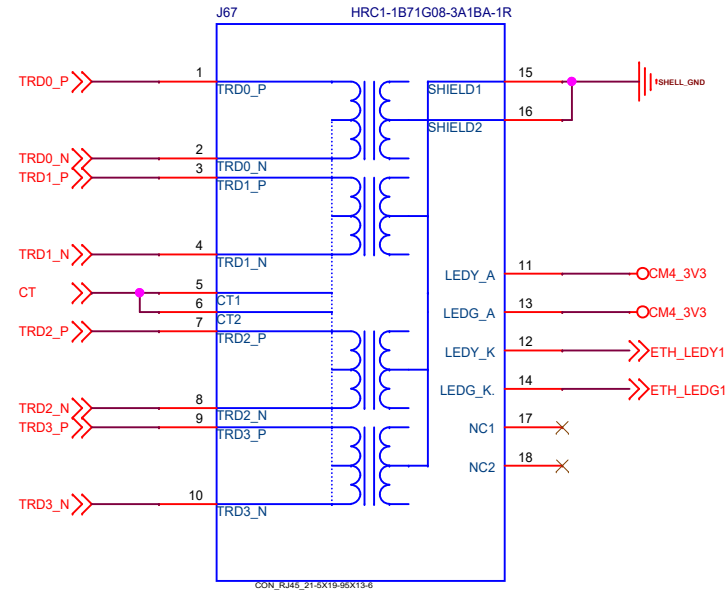


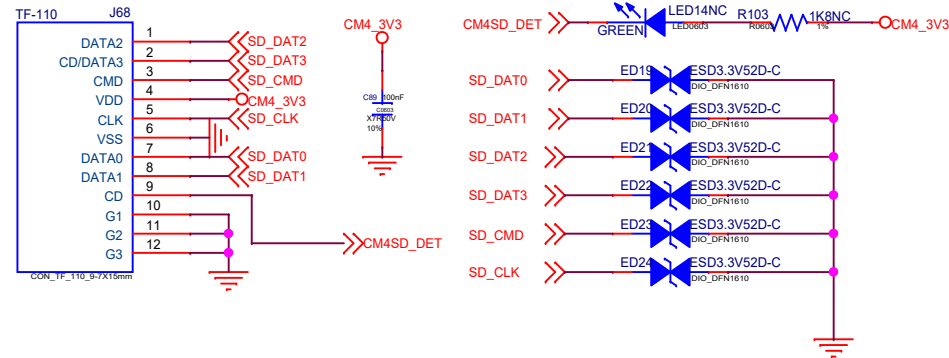
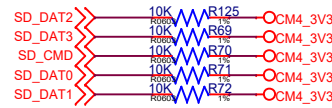




**ETHERNET ESD**

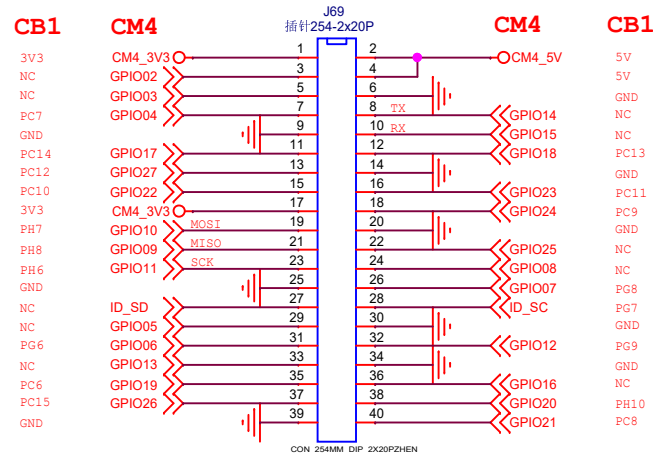
CB1 core board and CM4 core board are common.

**RJ45-100M&1000M**

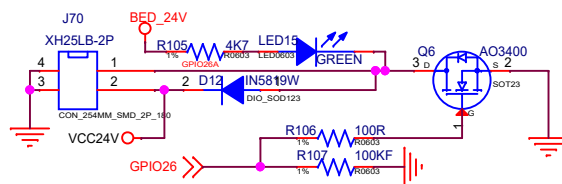


CB1 core board and CM4 core board are common.

## CB1&CM4 SD\_TF\_CARD



**CB1&M4P reserved IO**

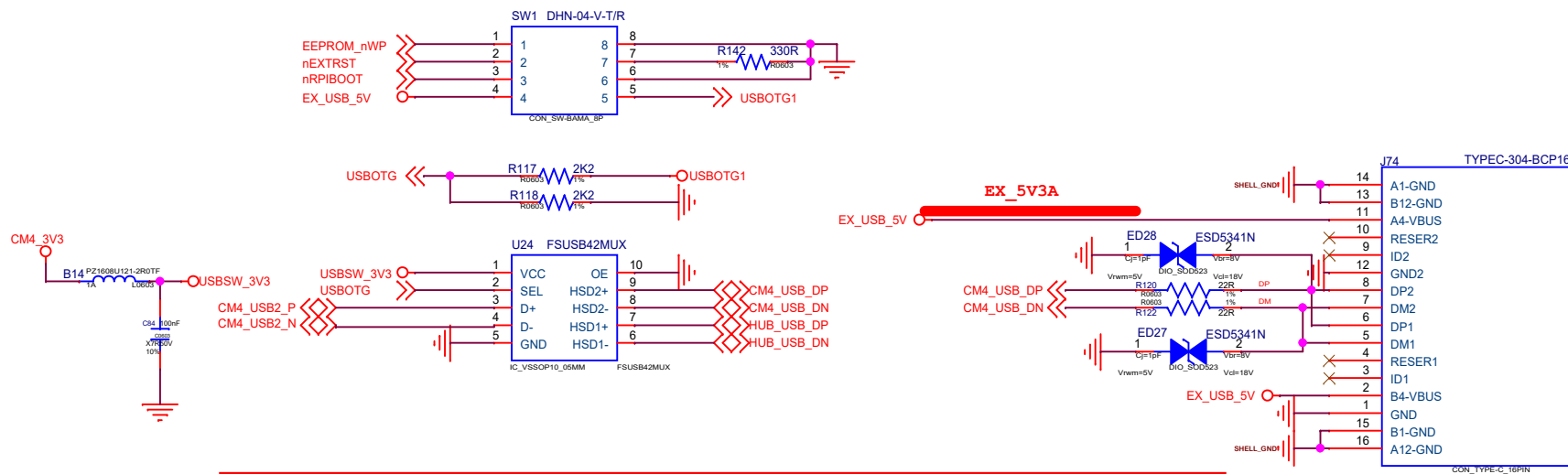


**CM4&CB1 FAN**



**Shenzhen Biqu Technology Co., Ltd.**

Title		Design
BIGHTREETECH_Manta_M4P_V2.1		Bron Bai
Size A4	Document Number	Rev
	23_CB1&CM_RESE_IO&CM4-FAN	V2.1
Date:	Thursday, July 07, 2022	Sheet 23 of 24



Sel	OE	Function
X	HIGH	Disconnect
LOW	LOW	D+, D- communicate with HSD1+, HSD1-, the core board communicates with the HUB;
HIGH	LOW	D+, D- communicate with HSD2+, HSD2-, the core board communicates with PC.